

Appl. No.: 10/561,883  
Amdt. Dated: December 2, 2009  
Reply to Office Action of September 2, 2009

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### AMENDMENTS

#### In the Specification:

Please add the following paragraphs at page 1, at the beginning of the Specification:

#### Cross-Reference to Related Applications

This application is derived from PCT patent application PCT/EP2004/007161 filed July 1<sup>st</sup> 2004 and claims priority from GB 0315623.9 filed July 3<sup>rd</sup> 2003.

#### Field of the Invention

This invention relates to die bonding.

#### Background of the Invention

Please insert the following heading on page 1, line 27 as follows:

#### Summary of the Invention

Please insert the following heading on page 4, line 21 as follows:

#### Brief Description of the Drawings

Please insert the following heading on page 5, line 4 as follows:

#### Detailed Description of Embodiments